

Divisional Application of  
Serial No. 10/232,678  
March 16, 2004  
Page 3 of 4

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-13 (canceled).

Claim 14 (original): A cavity-type integrated circuit package comprising:  
a premolded package body;  
a plurality of leads, each lead extending from an interior of said package body to an exterior thereof;  
a first semiconductor die mounted to a first side of a die attach pad, in a first cavity of said package body;  
a first plurality of wire bonds connecting various ones of said leads and said first semiconductor die;  
a first fill material substantially filling said first cavity of said package body;  
a second semiconductor die mounted to a second side of said die attach pad in said package body;  
a second plurality of wire bonds connecting various ones of said leads and said second semiconductor die;  
a second fill material covering a portion of said plurality of leads; and  
a lid for enclosing said second semiconductor die and said second plurality of wire bonds in said package body.

Claim 15 (original): The cavity-type integrated circuit package according to claim 14, wherein said first fill material is the same as said second fill material.